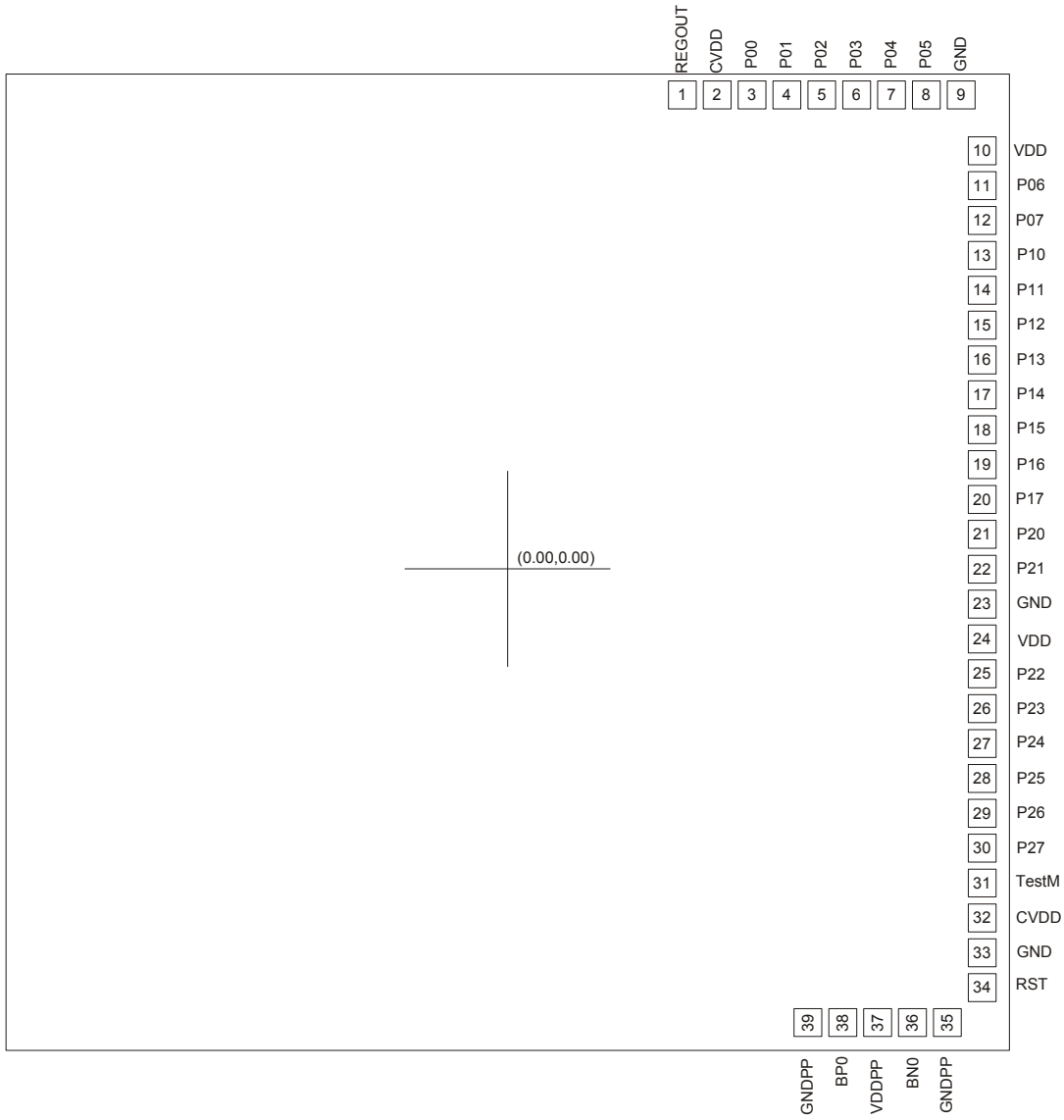




PROJECT: SNC82250B

NO	PAD NAME	X (um)	Y (um)	NO	PAD NAME	X (um)	Y (um)
1	REGOUT	325.08	1306.79	25	P22	1316.10	49.45
2	CVDD	432.28	1306.79	26	P23	1316.10	-30.55
3	P00	533.96	1306.79	27	P24	1316.10	-110.55
4	P01	613.96	1306.79	28	P25	1316.10	-190.55
5	P02	693.97	1306.79	29	P26	1316.10	-270.55
6	P03	773.97	1306.79	30	P27	1316.10	-350.55
7	P04	853.97	1306.79	31	TestM	1316.10	-430.55
8	P05	933.97	1306.79	32	CVDD	1316.10	-510.55
9	GND	1013.97	1306.79	33	GND	1316.10	-590.55
10	VDD	1316.10	1249.45	34	RST	1316.10	-670.55
11	P06	1316.10	1169.45	35	GNDPP	1262.40	-1298.00
12	P07	1316.10	1089.45	36	BN0	1152.40	-1298.00
13	P10	1316.10	1009.45	37	VDDPP	991.70	-1298.00
14	P11	1316.10	929.45	38	BP0	831.00	-1298.00
15	P12	1316.10	849.45	39	GNDPP	721.10	-1298.00
16	P13	1316.10	769.45				
17	P14	1316.10	689.45				
18	P15	1316.10	609.45				
19	P16	1316.10	529.45				
20	P17	1316.10	449.45				
21	P20	1316.10	369.45				
22	P21	1316.10	289.45				
23	GND	1316.10	209.45				
24	VDD	1316.10	129.45				



SNC82250B

CHIP SIZE: X=2720um, Y=2700um

Note: The substrate MUST be connected to GND in PCB layout.